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18099 (AT 20958-60)  
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IN THE CLAIMS:

1. (currently amended) An electronic package comprising:  
  
a circuit board;  
  
a compressible capsule layer encasing said circuit board and in intimate contact therewith, thereby forming a sealed immersible electronic module; and  
  
a housing receiving an outer surface of and press fit to said encapsulated electronic module and forming a protective shell around said electronic module with press fit engagement.
2. (original) An electronic package in accordance with claim 1 wherein said circuit board includes at least one sensor coupled thereto.
3. (original) An electronic package in accordance with claim 2 wherein said sensor is a hall effect sensor.
4. (currently amended) An electronic package in accordance with claim 1 wherein said compressible capsule layer comprises a melt processible rubber.
5. (previously presented) An electronic package in accordance with claim 1 wherein said housing comprises a longitudinal axis and an elongated opening extending transverse to said longitudinal axis for adjusting a position of said housing.
6. (previously presented) An electronic package in accordance with claim 1 wherein said housing comprises a mounting stud.

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7. (previously presented) An electronic package in accordance with claim 1, wherein said housing comprises at least one indicator bar.

8. (previously presented) An electronic package in accordance with claim 1 wherein one of said capsule layer and said housing comprises a latch configured to engage the other of said capsule layer and said housing.

9. (currently amended) An electronic package in accordance with claim 1 further comprising a magnetic plate, said magnetic plate positioned beneath said circuit board and encased in said capsule layer.

10. (currently amended) An electronic package comprising:

an electronic assembly overmolded with a capsule layer into a freestanding structure, said electronic assembly configured to output a signal in response to a condition of a monitored object;

a housing having a bore therein configured to receive said overmolded electronic ~~assembly~~, assembly via press fit insertion and

one of said capsule layer and said housing comprising a latch configured to engage the other of said capsule layer and said housing.

11. (currently amended) An electronic package in accordance with ~~claim 9~~ claim 10 wherein said housing comprises a longitudinal axis and a positioning aperture extending transversely to said longitudinal axis.

12. (currently amended) An electronic package in accordance with ~~claim 9~~ claim 10 wherein said electronic assembly includes at least one sensor.

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13. (currently amended) An electronic package in accordance with ~~claim 11~~ claim 12 wherein said sensor is a hall effect sensor.

14. (currently amended) An electronic package in accordance with ~~claim 9~~ claim 10 wherein said capsule layer comprises a melt processible rubber.

15. (currently amended) An electronic package in accordance with ~~claim 9~~ claim 10 wherein said housing comprises a longitudinal axis, and an elongated positioning opening extending transverse to said longitudinal axis.

16. (currently amended) An electronic package in accordance with ~~claim 9~~ claim 10 wherein said housing comprises a mounting stud.

17. (currently amended) An electronic package in accordance with ~~claim 9~~ claim 10 further comprising at least one indicator bar coupled to said housing to visually indicate the condition of the monitored object.

18. (currently amended) An electronic package in accordance with ~~claim 9~~ claim 10 wherein said electronic assembly comprises a magnetic plate, said magnetic plate positioned beneath said circuit board and encased in said capsule layer.

19. (currently amended) A method of packaging an electronic assembly subject to a severe operating environment, said method comprising:

encapsulating the electronic assembly to form a sealed immersible electronic module into a freestanding structure;

fitting the ~~enseapsulated~~ encapsulated electronic assembly into a housing shell; and

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securing the encapsulated module to the housing shell.

20. (currently amended) A method in accordance with ~~claim 18~~ claim 19 wherein said encapsulating the electronic assembly comprises overmolding the electronic assembly.

21. (previously presented) A method in accordance with ~~claim 19~~ claim 20 wherein said overmolding the electronic assembly comprises overmolding the electronic assembly with a melt processible rubber.

22. (previously presented) A method in accordance with ~~claim 18~~ claim 19 wherein fitting the encapsulated module to the housing shell comprises inserting the encapsulated module into a thixo-molded housing.

23. (previously presented) A method in accordance with ~~claim 18~~ claim 19 wherein fitting the encapsulated module to the housing shell comprises inserting an end of the encapsulated module into an end of the housing shell, and sliding the encapsulated module into the housing.

24. (previously presented) A method in accordance with ~~claim 18~~ claim 19 wherein one of the encapsulated module and the housing shell includes a latch member formed therein, said step of securing the encapsulated module to the housing shell comprising engaging the latch member to the other of the encapsulated module and the housing shell.

25. (previously presented) A method in accordance with ~~claim 18~~ claim 19 wherein the electronic assembly includes a cable, said step of encapsulating the electronic assembly to form an electronic module comprising overmolding the electronic assembly and a portion of the cable.